

CI RCUI T CONNECTI NG MATERI AL, FILM-LIKE CI RCUI T CONNECTI NG MATERI AL USI NG THE SAME, CI RCUI T MEMBER CONNECTI NG STRUCTURE, AND METHOD OF PRODUCI NG THE SAME

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Abstract of WO 2005002002 (A1)

The invention provides a circuit connecting material for connecting to each other a circuit member (30) having an electrode (32) and an insulation layer (33) formed adjacent each other on the surface (31a) of a substrate (31), and a circuit member (40) having an electrode (42) and an insulation layer (43) formed adjacent each other on the surface (41a) of a substrate (41), the edges (33a, 43a) of the insulation layers (33, 43) being thicker than the electrodes (32, 42) with the main surfaces (31a, 41a) used as references, wherein the circuit connecting material contains an adhesive agent composition (51) and electrically conductive particles (12) whose mean particle size is from 1 μm to less than 10 μm and whose hardness is 1.961 - 6.865 GPa, and when the circuit connecting material undergoes hardening process, its storage elasticity modulus at 40 $^{\circ}\text{C}$ is 0.5 - 3 GPa and its mean thermal expansion coefficient at 25 $^{\circ}\text{C}$ to 100 $^{\circ}\text{C}$ is 30 - 200 ppm/ $^{\circ}\text{C}$.

